

INTERNATIONAL STANDARD

IEC
62258-5

First edition
2006-08

Semiconductor die products –

**Part 5:
Requirements for information
concerning electrical simulation**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –**Part 5: Requirements for information
concerning electrical simulation**

FOREWORD

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International Standard IEC 62258-5 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard should be read in conjunction with IEC 62258-1 and IEC 62258-2.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1869/FDIS	47/1882/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The structure of IEC 62258, as currently conceived, consists of the following parts under the general title *Semiconductor die products*:

- Part 1: Requirements for procurement and use
- Part 2: Exchange data formats
- Part 3: Recommendations for good practice in handling, packing and storage (Technical Report)
- Part 4: Questionnaire for die users and suppliers (Technical Report) (in preparation)
- Part 5: Requirements for information concerning electrical simulation
- Part 6: Requirements for information concerning thermal simulation
- Part 7: XML schema for data exchange (Technical Report) (in preparation)

Further parts may be added as required.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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